

Cleanable no clean lead free solder paste

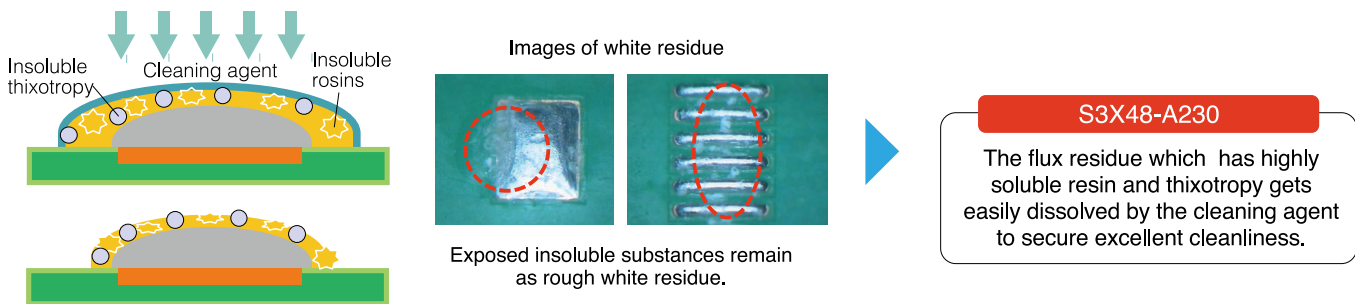
S3X48-A230 Sn 3.0Ag 0.5Cu

Exceptionally easy to clean with no trace of flux residue

Improves cleanability

If flux residues include substances unlikely to dissolve, or to be removed by cleaning agents, these will remain as "white residue". These residues may result in very poor cosmetic appearance as well as developing poor electrical reliability.

Figure 1. Mechanism of the formation of "white residue"

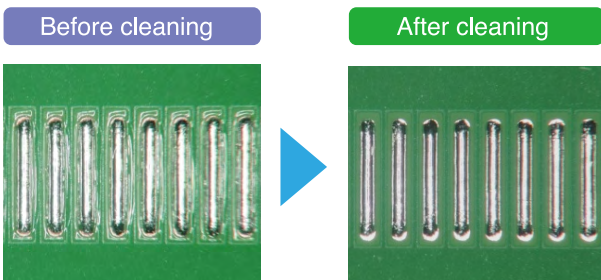


Suitable with most cleaning agents

S3X48-A230 is suitable for use with most cleaning agents and achieves remarkable cleanliness.

Figure 2. Cleanliness test

- Cleaning agent: ZESTRON Vigon A250
- Cleaning method: Stir PCB for 4 min. at 60°C → Rinse PCB with pure water



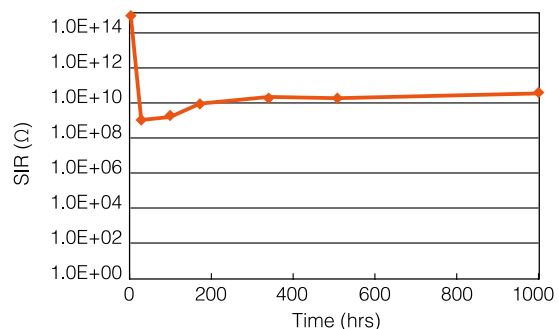
Flux residue on the PCB is completely removed only by stirring in the cleaning agent.

Also applicable for no clean PCBs

S3X48-A230 offers maximum flexibility to the assemblers by having the capability of both clean and no clean use.

Figure 3. Voltage applied SIR

- Test conditions: 85±2°C x 85%RH for 1000hrs + DC50V
- Test piece: JIS type-II



Product specifications

Product name	S3X48-A230
Alloy composition (%)	Sn 3.0Ag 0.5Cu
Melting point (°C)	217-219
Powder size (µm)	20-45
Viscosity (Pa.s)	210
Flux content (%)	12.0
Halide content (%)	0.06
Flux type	ROL1
Optional powder size	20-38µm (Product name: S3X58-A230)

- Flux residue cleanable
- Anti-pillow defect
- Low voiding
- Fine pitch printing >0.4mm pitch >0.3mm dia. CSP
- Tack time >24hours